

## Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard  
<http://www.ipc.org/IPC-175x>

Form Type\*  
 Distribute

**Declaration Class\***  
**Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information**

### Supplier Information

<b>Company Name *</b> Fairchild Semiconductor	<b>Company Unique ID</b> 00-489-5751	<b>Unique ID Authority</b> Dun & Bradstreet	<b>Response Date*</b> Sat, Aug 31, 2013 02:46 AM
<b>Contact Name *</b> David Lancaster	<b>Title - Contact</b> Product Ecology	<b>Phone - Contact *</b> 801-562-7455	<b>Email - Contact *</b> david.lancaster@fairchildsemi.com
<b>Authorized Representative *</b> David Lancaster	<b>Title - Representative</b> Product Ecology	<b>Phone - Representative *</b> 801-562-7455	<b>Email - Representative *</b> david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type
FDS9926A	FDS9926A	SOIC-8 (CuBW)			INTERNAL PENANG	0.087918	g	Each

### Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Matte Tin (Sn)	CU Alloy	1	260 C	30 seconds	3

\* Required Field

RoHS Material Composition Declaration		Declaration Type * Custom
<b>RoHS Directive</b> 2011/65/EU	<b>RoHS Definition:</b> Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium	
<p>This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.</p> <p>The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.</p> <p>Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.</p>		
<b>RoHS Declaration *</b>	<b>1 - Item(s) does not contain RoHS restricted substances per the definition above</b>	<b>Supplier Acceptance * Accepted</b>
<p><b>Exemptions:</b> If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.</p>		
<p>Exemption List Version EL-2011/534/EU None</p>		

#### Declaration Signature

Supplier Signature	 DAVID LANCASTER - PRODUCT ECOLOGY MANAGER
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# Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name SOIC-8 (CuBW)

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	7.100	Supplier		Silicon	7.100	7440-21-3	80757
Die Attach	Other Organic Materials	0.718	Supplier		Acrylic Resin	0.154	54208-63-8	1752
			Supplier		Silver	0.564	7440-22-4	6411
Encapsulation	Thermoplastics	39.400	B	Antimony/Antimony Compounds	Antimony Trioxide	0.788	1309-64-4	8963
			B	Brominated Flame Retardants (other than PBCs or PBDEs)	Bromine Resin	0.394	6386-73-8	4481
			Supplier		Carbon Black	0.296	1333-86-4	3361
			Supplier		Epoxy Resin	11.426	29690-82-2	129963
			Supplier		Silica, vitreous	26.496	60676-86-0	301379
Lead Frame	Copper & its alloys	38.600	Supplier		Copper	37.531	7440-50-8	426886
			Supplier		Iron	0.926	7439-89-6	10537
			Supplier		Phosphorus	0.015	7723-14-0	176
			Supplier		Silver	0.077	7440-22-4	878
			Supplier		Zinc	0.050	7440-66-6	571
Plating	Other Nonferrous metals & alloys	2.000	Supplier		Tin	2.000	7440-31-5	22749
Wire Bond	Copper & its alloys	0.100	Supplier		Copper	0.100	7440-50-8	1137